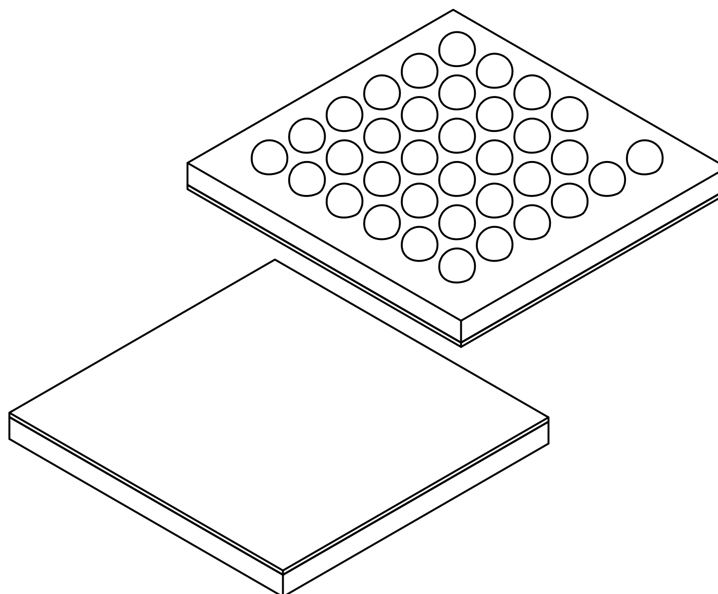
35-Ball Wafer Level Chipscale Package (GUB) - 2.916x2.831 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		35	
Pitch	e		0.40 BSC	
Overall Height	A	0.403	0.443	0.483
Ball Height	A1	0.17	0.20	0.23
Die Thickness	A2	0.178	0.203	0.228
Film Thickness	A3	0.036	0.040	0.044
Overall Length	D		2.831 BSC	
Overall Pitch	eD		2.00 BSC	
Overall Width	E		2.916 BSC	
Overall Pitch	eE		2.00 BSC	
Ball Diameter	b	0.24	0.27	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.